




PCN Number:	20190801000.1		PCN Date:	Aug 2 2019												
Title:	Qualification of TI Philippines (TIPI) as an alternate Assembly site for Select Devices in the DBV package															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	Nov 2 2019	Estimated Sample Availability:	Date provided at sample request													
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
Texas Instruments is pleased to announce the qualification of TI Philippines (TIPI) as an Additional Assembly site for the list of devices shown below. Current assembly sites and Material differences are as follows:																
<table border="1"> <thead> <tr> <th></th> <th>Lingsen</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>SID#0003C10332</td> <td>4207123</td> </tr> <tr> <td>Mold Compound</td> <td>SID#0011G60007</td> <td>4222198</td> </tr> <tr> <td>Bond wire composition/diameter</td> <td>Au, 1.0 mils</td> <td>Cu, 1.0 mils</td> </tr> </tbody> </table>						Lingsen	TIPI	Mount Compound	SID#0003C10332	4207123	Mold Compound	SID#0011G60007	4222198	Bond wire composition/diameter	Au, 1.0 mils	Cu, 1.0 mils
	Lingsen	TIPI														
Mount Compound	SID#0003C10332	4207123														
Mold Compound	SID#0011G60007	4222198														
Bond wire composition/diameter	Au, 1.0 mils	Cu, 1.0 mils														
Reason for Change:																
Continuity of Supply																
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																
None																
Anticipated impact on Material Declaration																
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp													
Changes to product identification resulting from this PCN:																
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City													
Lingsen	LIN	TWN	Taichung													
TIPI	PHI	PHL	Baguio City													
Sample product shipping label (not actual product label)																

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLV3401CDBVR	TLV3401IDBVR	TLV3401IDBVT	TLV3401IDBVTG4
TLV3401CDBVT	TLV3401IDBVRG4		



TI Information
Selective Disclosure

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV3401IDBVT	QBS Product Reference : TLV2241D	QBS Package Reference : TPS76933DBVR
AC	Autoclave 121C	96 Hours	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	1/Pass	-	-
HAST	Biased HAST, 110C/85%RH	96 Hours	-	-	3/231/0
HTOL	Life Test, 155C	240 Hours	-	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/231/0
HBM	ESD-HBM	2000 V	1/3/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	1/Pass	-	-
MQ	Test MQ	(per specification)	Pass	-	-
YLD	Yield Evaluation	(per mfg. Site specification)	Pass	-	-

- QBS: Qual By Similarity
- Qual Device TLV3401IDBVT is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
 Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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